

注記 NOTES

1. 使用材料 MATERIAL  
 ハウジング : 液晶ポリマー ( LCP ) UL94V-0 ( 黒 )  
 60極品はLCPのグレードが異なります。  
 HOUSING: LIQUID CRYSTAL POLYMER UL94V-0 ( COLOR: BLACK )  
 ターミナル : 銅合金  
 TERMINAL : COPPER ALLOY  
 金具 : 銅合金  
 FITTING NAIL : COPPER ALLOY

- △ (全極数 / 2) = 偶数の場合に適用。  
 APPLY FOR (CIRCUIT/2)-EVEN.
4. 嵌合相手 : 503304 シリーズ  
 MATE WITH : 503304 SERIES.
  5. テール平坦度は、0.08 以下  
 テール及び金具の平坦度は、0.1 以下  
 TAIL COPLANARITY TO BE 0.08 MAXIMUM.  
 TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.

2. メッキ仕様 PLATING

ターミナル TERMINAL

- 金メッキ  
GOLD
- 下地メッキ : ニッケルメッキ  
UNDER PLATING : NICKEL

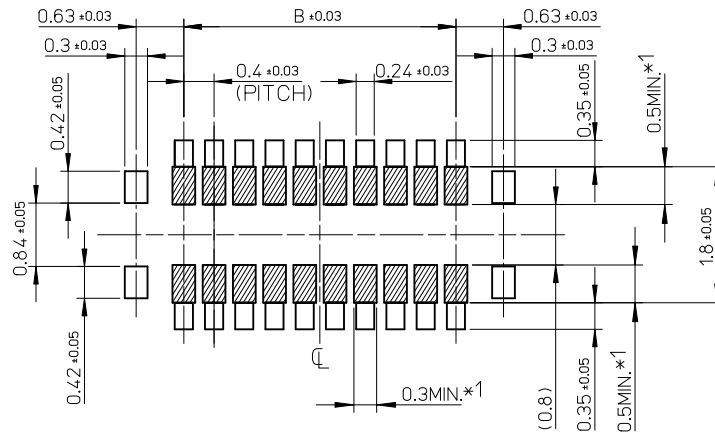
※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。  
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.

金具 FITTING NAIL

- 錫メッキ  
Tin PLATING
- 下地メッキ : ニッケルメッキ  
UNDER PLATING : NICKEL

11.6	13.47	503308-6020	60
9.6	11.47	503308-5010	50
8.4	10.27	503308-4410	44
8.0	9.87	503308-4210	42
7.6	9.47	503308-4010	40
5.6	7.47	503308-3010	30
4.8	6.67	503308-2610	26
4.4	6.27	503308-2410	24
3.6	5.47	503308-2010	20
3.2	5.07	503308-1810	18
2.8	4.67	503308-1610	16
2.0	3.87	503308-1210	12
B	A	EMBOSSSED PACKAGE	
		オーダー番号 ORDER No.	極数 CIRCUITS
CONNECTOR SERIES No. : 503308-**09			

REVISED EC NO: J2011-0495 DRWN: M. AKAHASHI 03/20/10/05/14 CHKD: 20/10/05 APPR: MSASAO 20/10/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KSASAKI	DATE 2008/04/17	TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y		
	10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA	DATE 2008/04/17	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2008/04/17	DOCUMENT NO. SD-503308-001		
	ANGULAR ±1 °		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



\*1 パターン引き回し、および半田禁止エリア  
 (当該箇所においては、これと接する回路以外の配線を禁止する。  
 また、接する回路を配線する場合はレジストを施し、この部分に  
 半田は無きこととする。)

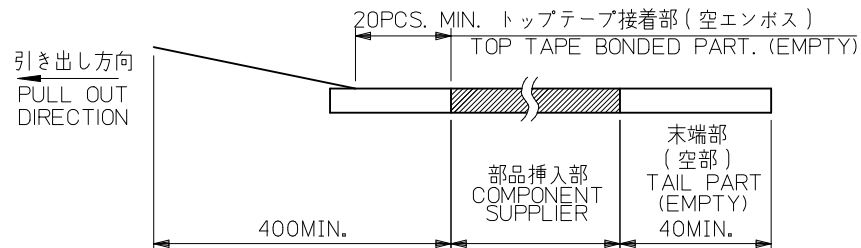
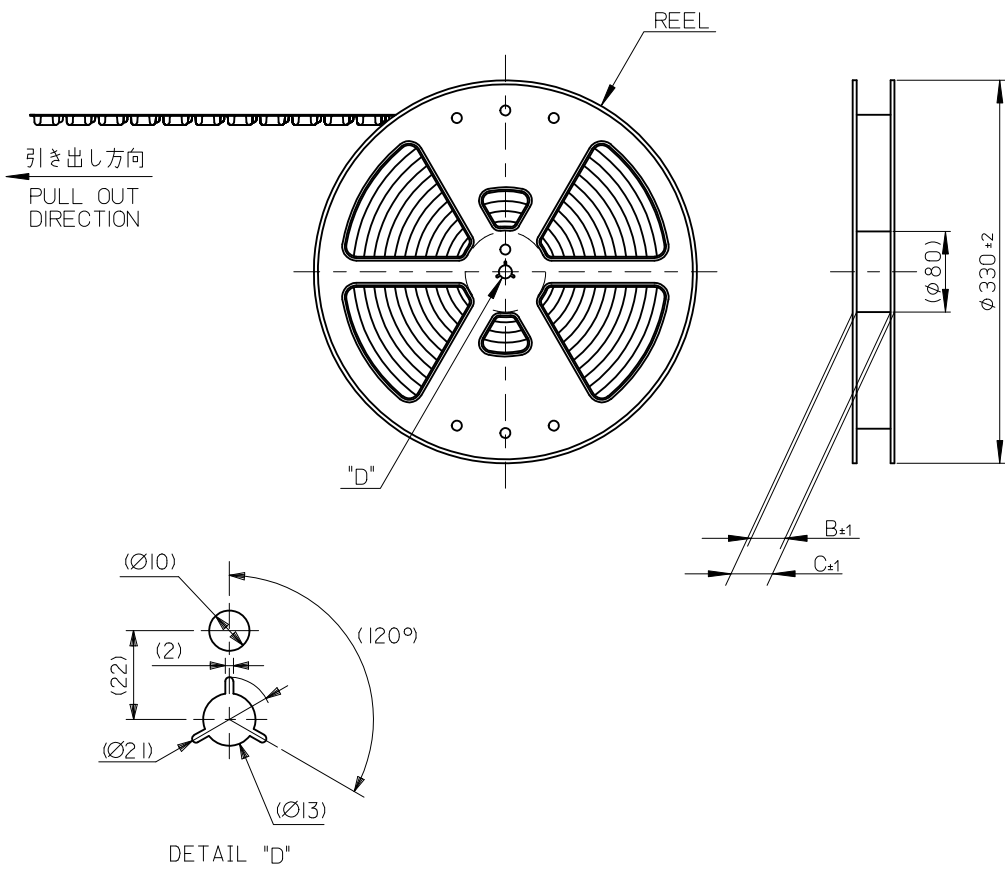
\*1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.  
 (FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER  
 CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

RECOMMENDED P.W. BOARD  
 PATTERN LAYOUT

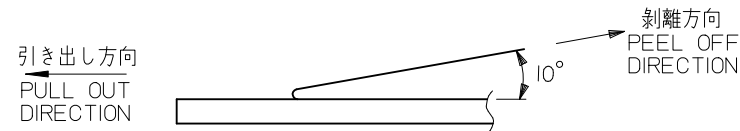
REVISED EC NO: J2011-0495 DRWN: MTAKAHASHI 2010/05/14 CHKD: 2010/10/05 APPR: MSASAO 2010/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY KSASAKI	DATE 2008/04/17	TITLE 0.4 B-TO-B CONN. HGT=0.7 W=2.6 PLUG ASS'Y			
	10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2008/04/17				
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2008/04/17	MOLEX INCORPORATED			
ANGULAR ± 1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503308-001				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

注記 NOTES

- 製品詳細寸法については製品単体図面を参照下さい。  
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 3000 個/リール  
NUMBER OF CONNECTORS: 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



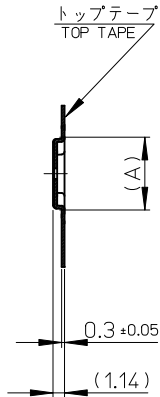
- トップテープの剥離強度: 0.1N~1.3N(10gf~130gf)  
(剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE: 0.1N~1.3N(10gf~130gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.



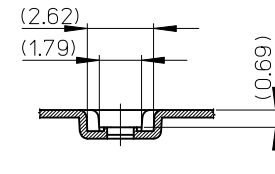
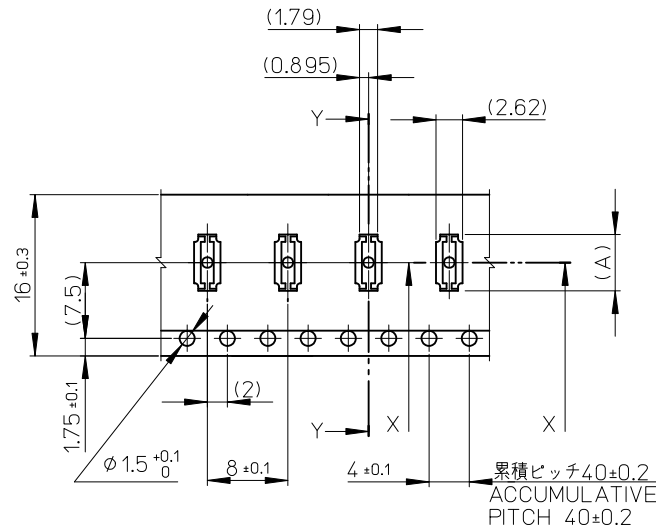
- 材料 MATERIAL  
キャリアテープ (CARRIER TAPE): ポリスチレン (POLYSTYRENE)  
トップテープ (TOP TAPE): PET, OTHER  
リール (REEL): ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品  
ELV AND RoHS COMPLIANT

REVISED EC NO: J2011-0495 DRWN:KSASAKI CHKD: APPR:MSASAO	DESCRIPTION 2010/08/16 2010/10/05 2010/10/05	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	MODEL NO.	503308-**10
		10 UNDER	±0.2	DRAWN BY KSASAKI		DATE 2008/12/12	TITLE	THIRD ANGLE PROJECTION	
		10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA		DATE 2008/12/12	0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG		
		30 OVER	±0.3	APPROVED BY MSASAO		DATE 2008/12/12	MOLEX INCORPORATED		
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503308-002	SHEET NO. 1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

引き出し方向  
PULL OUT DIRECTION



SECTION Y-Y

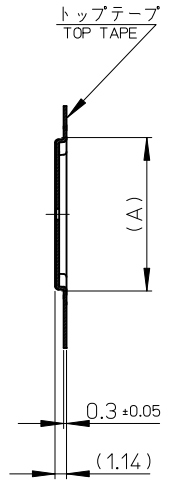


SECTION X-X

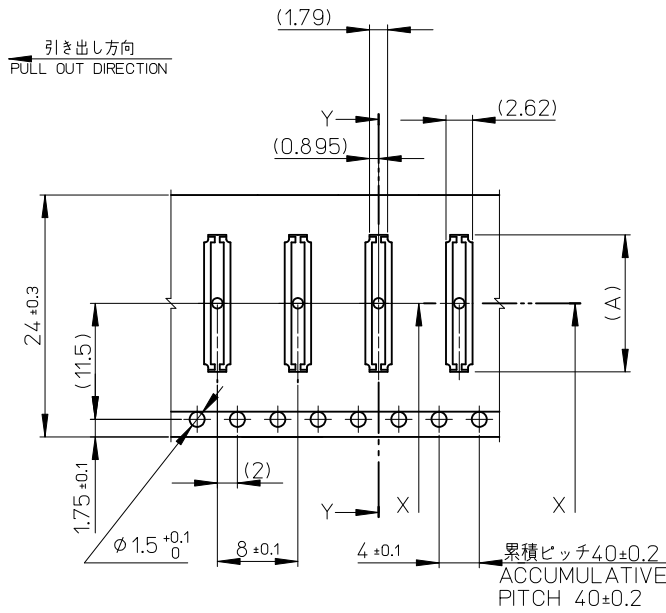
16mm 幅キャリアテープ  
16mm WIDTH CARRIER TAPE

16	21.4	17.4	6.79	503308-2610	26
			6.39	503308-2410	24
			5.59	503308-2010	20
			5.19	503308-1810	18
			4.79	503308-1610	16
			3.99	503308-1210	12
キャリアテープ幅 CARRIER TAPE WIDTH			C	B	(A)
			MATERIAL No.		CKT.
			MODEL No.		503308-**-10

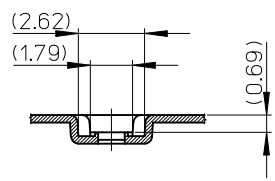
REVISED EC NO: J2011-0495 DRWN:KSASAKI CHKD: APPR:MSASAO 2010/08/16 2010/10/05 2010/10/05	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY DATE		TITLE		MOLEX INCORPORATED 0.4 B-TO-B CONN. HGT=0.7 PLUG ASSY EMBSTP PKG		
		10 OVER 30 UNDER	± 0.25	CHECKED BY DATE		DRAWN BY DATE				
		30 OVER	± 0.3	APPROVED BY DATE		CHECKED BY DATE		DOCUMENT NO.		SHEET NO.
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SD-503308-002		2 OF 3		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



SECTION Y-Y



累積ピッチ 40±0.2  
ACCUMULATIVE PITCH 40±0.2



SECTION X-X

24mm 幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	29.4	25.4	13.59	503308-6020	60
			11.59	503308-5010	50
			10.39	503308-4410	44
			9.99	503308-4210	42
			9.59	503308-4010	40
			7.59	503308-3010	30
キャリアテープ幅 CARRIER TAPE WIDTH			C	B	(A)
			MATERIAL No.		CKT.
			MODEL No.		503308-**-10

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		10 OVER 30 UNDER	± 0.25	KSASAKI 2008/12/12					
		30 OVER	± 0.3	CHECKED BY DATE					
ANGULAR ± 1 °		APPROVED BY DATE		MSASAO 2008/12/12		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE CHART		SD-503308-002		3 OF 3	